



Wide-Bandgap Materials for Photonic and Phononic Applications

Guest Editors:

Dr. Yanan Wang

College of Engineering, Electrical
& Computer Engineering,
University of Nebraska-Lincoln,
Lincoln, NE 68588, USA

Dr. Ufuk Kilic

College of Engineering, Electrical
& Computer Engineering,
University of Nebraska-Lincoln,
Lincoln, NE 68588, USA

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Message from the Guest Editors

Dear Colleagues,

This Special Issue seeks to celebrate the advances in wide-bandgap materials, including, but not limited to, diamond, silicon carbide (SiC), gallium nitride (GaN), aluminum nitride (AlN), lithium niobate (LiNbO₃), hexagonal boron nitride (h-BN), and gallium oxide (Ga₂O₃), as well as to showcase research papers, communications, and review articles related to their applications in photonics and phononics. Theoretical studies (such as first-principle prediction and device design) and experimental works (such as materials synthesis and characterization, device fabrication and measurements, system integration and packaging) are all considered to be within the scope of this Special Issue.

Keywords

- wide-bandgap materials (WBMs)
- photonics
- optics
- phononics
- acoustics
- nano-/micro-electromechanical systems (N/MEMSs)





Editor-in-Chief

Message from the Editor-in-Chief

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Micromachines Editorial Office
MDPI, St. Alban-Anlage 66
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